



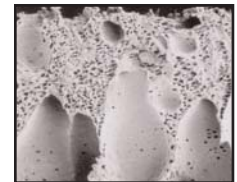
# Finishing Pads

## DESCRIPTION

All poromeric pads are designed to produce a featureless, exacting surface finish. Developed through laboratory and customer testing, each product has unique polishing characteristics based on combinations of the elements of pore structure, urethane density and substrate composition. These unique characteristics allow finishing pads to work effectively under a wide variety of polishing conditions and permit maximum compatibility with individual processes.

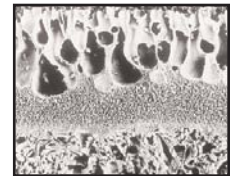
### SPM3100

The newest poromeric technology developed for silicon final polishing, the SPM3100 features a proprietary pore structure grown directly on a Mylar substrate. The simplicity of this design combined with the unique pore structure reduces variations in pad physical properties, ultimately leading to more consistent performance throughout the life of the pad and a much lower nanoscratch level. The SPM3100 is recommended as a final pad for all polishing operations where surface finish is most critical as defined by haze, microscratches, roughness and light point defects.



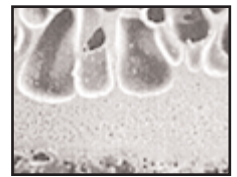
### DPC6350

DPC6350 is a grown-in-place poromeric on a urethane impregnated substrate that incorporates a vertically-oriented pore structure similar to the Politex® Supreme material, yet with a moderately less compressible and thinner substrate. This combination provides optimum removal rate and surface finish while maintaining dub-off when polishing nickel plated memory disks and glass substrates. DPC6350 is an improved version of the industry standard, Politex™ DG, providing more consistent pore structure within lots of material and lot-to-lot. The smoother finish makes this an excellent pad for final polish due to lower microwaviness, roughness, and faster break-in.



### Politex Supreme

Politex™ Supreme, was originally developed for final wafer polishing. It is manufactured from proprietary polyurethane and incorporates a unique, vertically oriented pore structure with a compressible substrate. The substrate is designed to instantaneously recover from polishing compression, creating a pumping action that enhances slurry flow within the pad to produce optimum surface finish quality. This attribute reduces pad loading and increases pad life. This pad is available with a longer nap height which is well suited for final polishing of silicon, oxide, glass or metals.



## TYPICAL PAD PROPERTIES

Product	Thickness	Pore Height	Microporous	Pore Count
Politex™ Supreme High Nap.	0.060"	0.020"	0.006"	N/A
Politex™ Supreme Regular Nap	0.056"	0.015"	0.006"	N/A
SPM 3100	0.028"	0.0205"	N/A	N/A
DPC6350	0.041"	0.020"	0.008"	400

These values represent typical measurements. Actual values may vary in a range defined by product specifications.



creating the  
**flawless** surface

## PLATEN APPLICATION

Only apply to a clean, dry surface at room temperature. If an appropriate solvent, such as isopropyl alcohol, is used to clean the platen after pad removal, allow the platen to dry completely and return to room temperature before applying a new pad. The adhesion of the pressure-sensitive adhesive (PSA) to the platen could be weakened if the pad is applied to an unusually cool platen or if solvent remains on the platen.

When applying the pad to the platen, peel the release liner from one edge of the pad, fold the liner back approximately 5 cm (2 inches), align the pad with the edge of the platen and adhere. In one continuous movement, slowly peel the remaining release liner off the pad while pressing the pad down on the platen. The application should be smooth and uniform, using even pressure from a pad mounting tool such as a flat disk or hand roller.

Do not try to reposition a pad that is mounted with PSA II adhesive.

Pads with PSA 4 and 9 are repositionable PSAs and can be moved during mounting as necessary.

## PACKAGING

Pads are shipped with PSA backing with a non-particulate release liner. Each pad is double bagged to ensure cleanliness is maintained during transportation.

## SHELF LIFE

Standard shelf life for all pads is one (1) year from the date of manufacture.

## STORAGE

All pads should always remain flat. Bending pads during handling can cause wrinkles in the PSA and premature delamination of the release liner. All pads should be stored and transported in their original packaging. This product should be stored in temperatures between 10°C to 24°C (50°F to 75°F) and <50% humidity. Exposure for six (6) months or less to conditions between -17°C to 48°C (0°F to 120°F) and/or at relative humidity of up to 100% will not impact product performance as long as the release liner remains intact and attached to the PSA. If the product is exposed to temperatures and humidity outside the recommended conditions, it may still be acceptable for use—please contact your Rohm and Haas Electronic Materials technical representative for recommendations. In all cases the product should be allowed to return to room temperature prior to use.

## PRECAUTIONARY NOTES

Follow all MSDS and label precautions as well as good industrial hygiene practices when handling or using this product. Keep this and all industrial materials away from untrained personnel.

## DISPOSAL

Dispose in accordance with all applicable regulations.

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